

AMENDMENTS TO THE SPECIFICATION:

Pleas replace the paragraph beginning at page 1, line 11 with the following rewritten paragraph:

-- This application is a divisional of U.S. Ser. No. 09/969,531 filed October 1, 2001 now U.S. Patent No. 6,649,523 which claims the benefit of prior U.S. Provisional Application Serial No. 60/236,505, filed September 29, 2000, which is ~~hereby~~ all incorporated herein by reference herein. --

Page 6, please delete the second full paragraph starting on line 9 and replace with the following rewritten paragraph:

-- A method of removing a material from a surface of a workpiece using a reactive pad positioned sufficiently near to the workpiece, such that the reactive pad barely touches the surface of the material to be removed, and so that the reactive pad is subjected to near zero deformation or non-significant deformation with respect to its thickness, ~~is presented according to a further aspect of the present invention.~~ The reactive pad and the workpiece may vibrate or move mechanically with respect to each other during the material removal process.--

Page 6, please delete the third full paragraph starting on line 15 and replace with the following rewritten paragraph:

-- A method of removing a material from a surface of a workpiece using a combination pad, is presented according to another aspect of the present invention. The combination pad material is a combination of a reactive pad and a conventional mechanical pad, such that some portions of the combination pad material include a reactive pad material and other portions of the combination pad material include conventional mechanical pad material. During the material planarization process, the workpiece is positioned very close to the pad so as to be in contact with the combination pad material. Both the workpiece and the combination pad material move with respect to each other.--

Page 7, please delete the first full paragraph starting on line 1 and replace with the following rewritten paragraph:

-- A method and arrangement of removing a material from a surface of a workpiece using a combination of a reactive pad and a mechanical pad, such that the reactive pad is positioned adjacent to a mechanical pad, is presented according to a further aspect of the present invention. During planarization of the workpiece, the workpiece may vibrate or move mechanically with respect to the pad. Some portions of the material on the workpiece are removed using the reactive pad, while other portions of the material are removed using the mechanical pad.--

Page 16, please delete the paragraph starting on line 18 and replace with the following rewritten paragraph:

-- In another embodiment according to the present invention, an arrangement consisting of the combination of a reactive pad positioned adjacent to a mechanical pad is described. Referring now to FIG. 5, it is a diagram illustrating a partial view of a front surface **318** of an exemplary embodiment **310** of the reactive pad **210** of FIG. 3 that includes a combination of reactive and mechanical pad material. As shown in FIG. 5, strips **302, 304** of reactive **302** and mechanical **304** pad are disposed as alternating layers in the pad **310**. Of course, different geometrical arrangements or configurations may be used. For example, reactive pad portions **302** preferably range between five to seventy percent, the balance being a conventional mechanical pad portions **304**, or vice versa. During the planarization process, portions of the material **B 206** to be removed are removed by the reactive pad sections **302**, while other portions are removed by the mechanical pad sections **304**.--